



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Rich Fogal and Michael B. Ball

Serial No.: 09/422,887

Filed: October 21, 1999

For: ANGULARLY OFFSET STACKED DIE  
MULTICHIP DEVICE AND METHOD OF  
MANUFACTURE

§ Group Art Unit: 2822

§ Examiner: J. Davis

§ Atty. Docket: 95-0134.05

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FIRST AMENDMENT AND RESPONSE TO THE  
OFFICE ACTION DATED MAY 24, 2000

Certificate of Mailing (37 C.F.R. § 1.8)

Assistant Commissioner for Patents  
Washington, D.C. 20231

Dear Sir:

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail, postage prepaid, in an envelope addressed to: Assistant Commissioner for Patents, Washington, D.C. 20231, on the date below.

5/24/00

*Rich Fogal - Vander*

Signature

Date

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IN THE SPECIFICATION:

Please delete the following text added in the Preliminary Amendment,

"Related Applications"

This application is a divisional of application serial number 09/122,666, filed July 24, 1998; which is a continuation of application serial number 08/741,579, filed November 1, 1996 and issued on February 23, 1999 as U.S. Patent No. 5,874,781; which is a continuation of application serial number 08/515,719, filed August 16, 1995 and now abandoned."